

This amendment is accompanied by and is intended to fulfill the submission requirement for the accompanying Request for Continued Examination. Accordingly, this amendment should be entered.

Please amend the application as follows:

IN THE CLAIMS

Please amend claim 20 as follows:

B¹ 20. (Amended) A semiconductor device provided with:

a resin member of a predetermined thickness, said resin member being made of a seal resin;

a semiconductor element sealed inside said resin member, having a back surface exposed at a top surface of said resin member, and having an active surface facing downward;

metal interconnections formed directly on the bottom surface of the resin member; and

connection terminals extending downward from the active surface of the semiconductor element and having bottom ends connected to top surfaces of said metal interconnections.

Please add the following new claim:

B² 39. (New) A semiconductor device as set forth in claim 21, wherein the top surface of said resin member and the back surface of said semiconductor element are ground to form substantially the same plane.